

**TAZMO**

# Q2 FY2025 Financial Announcement

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August 8, 2025

Security Code 6266

Company Guide



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# Q2 FY2025 Consolidated Financial Summary

## Net sales

**16,787**

Million Yen

YoY Change +3.4%

## Operating income

**2,517**

Million Yen

YoY Change  $\triangle$ 11.2%

## Ordinary income

**2,384**

Million Yen

YoY Change  $\triangle$ 20.0%

## Net income(\*)

**1,645**

Million Yen

YoY Change  $\triangle$ 20.4%

### ■ Overview

- Net sales fell short of the plan, mainly due to inspection delays in the Process Equipment Business. However, operating profit exceeded the plan as a result of cost reductions and improved profitability from mass production of semiconductor equipment.
- In the Surface Treatment Equipment Business and the Precision Molding Dies and Plastic Moldings Business, projects that had undergone productivity improvements were inspected and accepted.
- In the Process Equipment Business, order intake has not achieved the expected level amid a wait for market recovery. While orders for semiconductor equipment for advanced packaging are showing a slower-than-expected pace, an increase is anticipated in the second half.

(\*) Net income: Net income attributable to owners of parent

# Q2 FY2025 Financial Summary

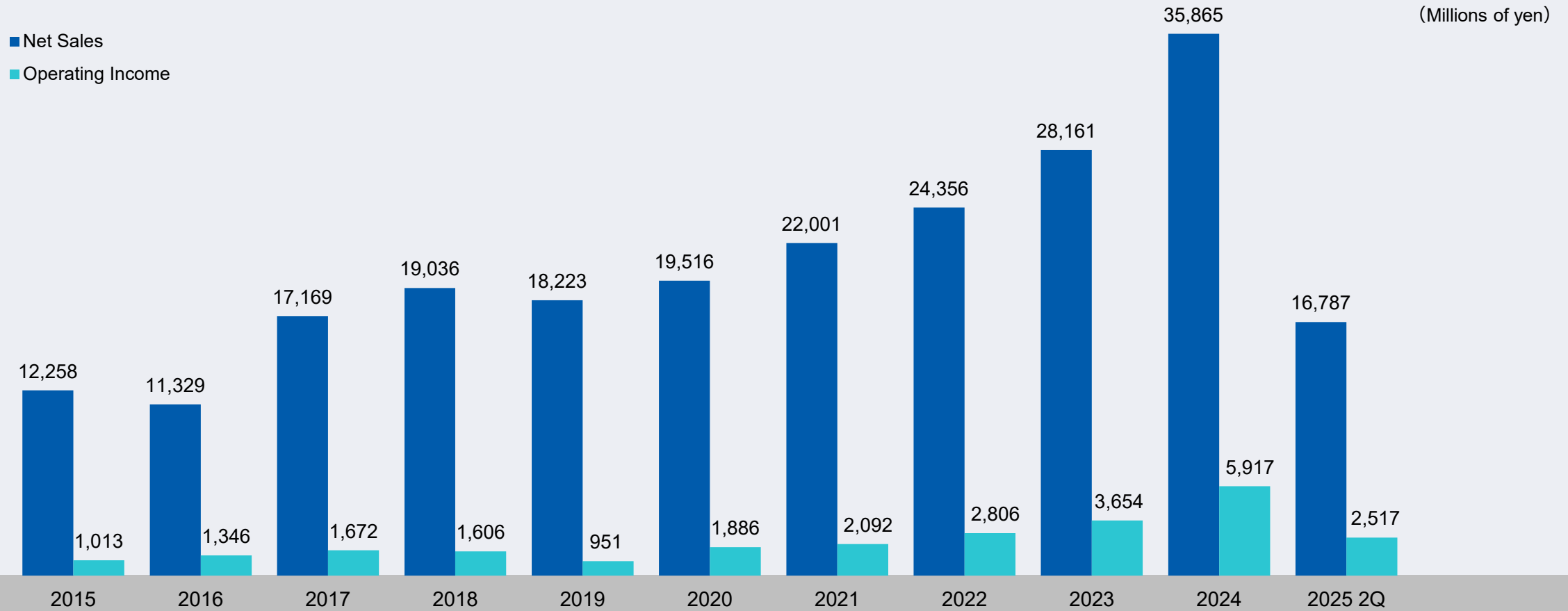
Year-on-year, profit declined due to lower sales of high-margin equipment for power semiconductors. Against the plan, however, we achieved a substantial increase in profit, exceeding expectations, driven by improved production efficiency and other factors.

(Millions of yen)	Q2 FY2024 Actual	Q2 FY2025		YoY change (%)	FY2025 Initial H1 Estimate	vs. Initial H1 Estimate (%)	FY2025 Full Year Estimate	vs. Full Year Estimate (%)
		Actual	Net sales ratio (%)					
<b>Net sales</b>	16,239	16,787	—	3.4	18,640	90.1	41,000	40.9
<b>Gross profit</b>	5,534	5,231	31.2	△5.5	—	—	—	—
<b>Operating income</b>	2,836	2,517	15.0	△11.2	1,930	130.4	5,000	50.3
<b>Ordinary income</b>	2,981	2,384	14.2	△20.0	1,920	124.2	5,100	46.7
<b>Net income attributable to owners of parent</b>	2,067	1,645	9.8	△20.4	1,350	121.9	3,500	47.0

# Trend in Net sales and Operating profit (Quarterly)



# Trend in Net sales and Operating profit (Full year)



(Millions of yen)	FY2024 Actual	Q2 FY2025 Actual	YoY change(%)
Current assets	40,731	39,983	△747
Non-current assets	8,469	8,563	93
Property, plant and equipment	7,385	7,448	63
Intangible assets	156	166	9
Investments and other assets	927	948	20
<b>Total assets</b>	<b>49,200</b>	<b>48,547</b>	<b>△653</b>
Current Liabilities	17,696	16,968	△727
Non-Current Liabilities	6,861	6,958	97
<b>Total liabilities</b>	<b>24,557</b>	<b>23,927</b>	<b>△630</b>
<b>Total net assets</b>	<b>24,642</b>	<b>24,619</b>	<b>△22</b>
Equity ratio	49.1%	49.9%	0.8P

## Major Change

( Millions of yen )

### Current Assets

Cash and deposits	+2,653
Notes and accounts receivable - trade	△950
Inventories	△1,232

### Current Liabilities

Electronically recorded obligations – operating	△2,004
Contract liabilities	+1,455
Short-term borrowings	+329
Income taxes payable	△347

### Non-Current Liabilities

Long-term borrowings	+159
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(Millions of yen)	Q2 FY2024 Actual	Q2 FY2025 Actual	YoY change(%)
Cash flow from operating activities	4,353	4,394	41
Cash flow from investing activities	△971	△4,540	△3,569
Free cash flow	3,382	△145	△3,528
Cash flow from financing activities	△1,927	△556	1,371
Cash on hand	8,589	8,719	130

## Highlights

( Millions of yen )

### Cash flow from operating activities

Profit before income taxes	2,400
Contract Liabilities	1,597
Trade payables	△1,897
Trade receivables	1,650

### Cash flow from investing activities

Net increase in time deposits	△3,759
Purchase of property, plant and equipment	△749

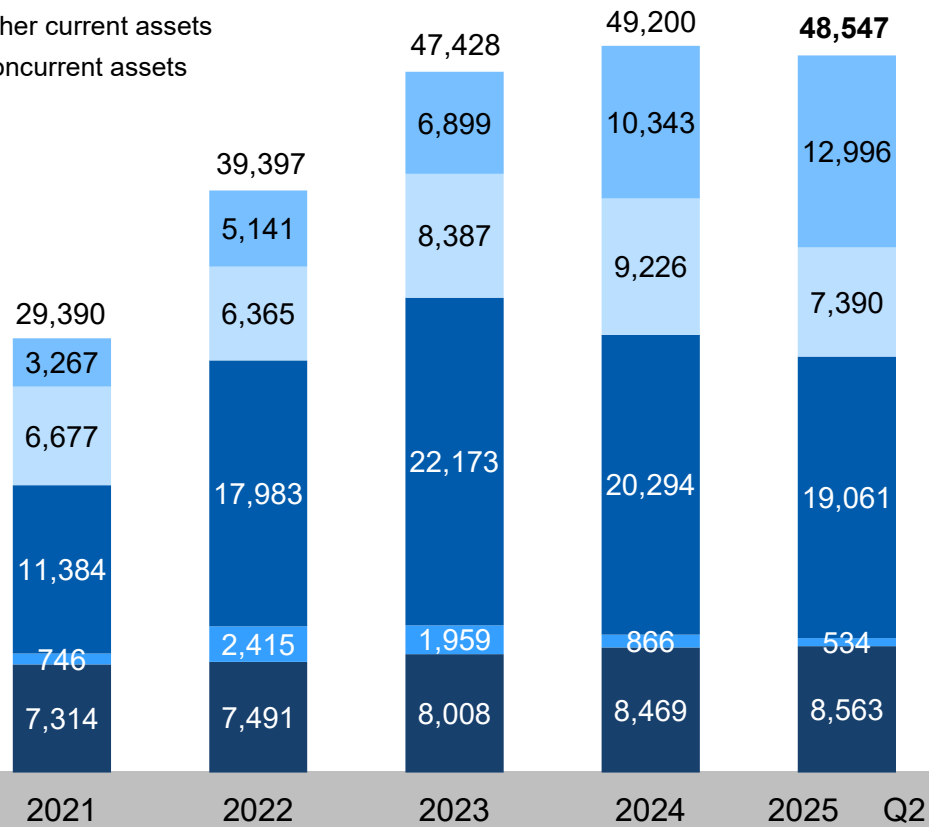
### Cash flow from financing activities

Proceeds from long-term borrowings	2,000
Repayments of long-term borrowings	△1,510
Purchase of treasury shares	△511

## Assets

(Millions of yen)

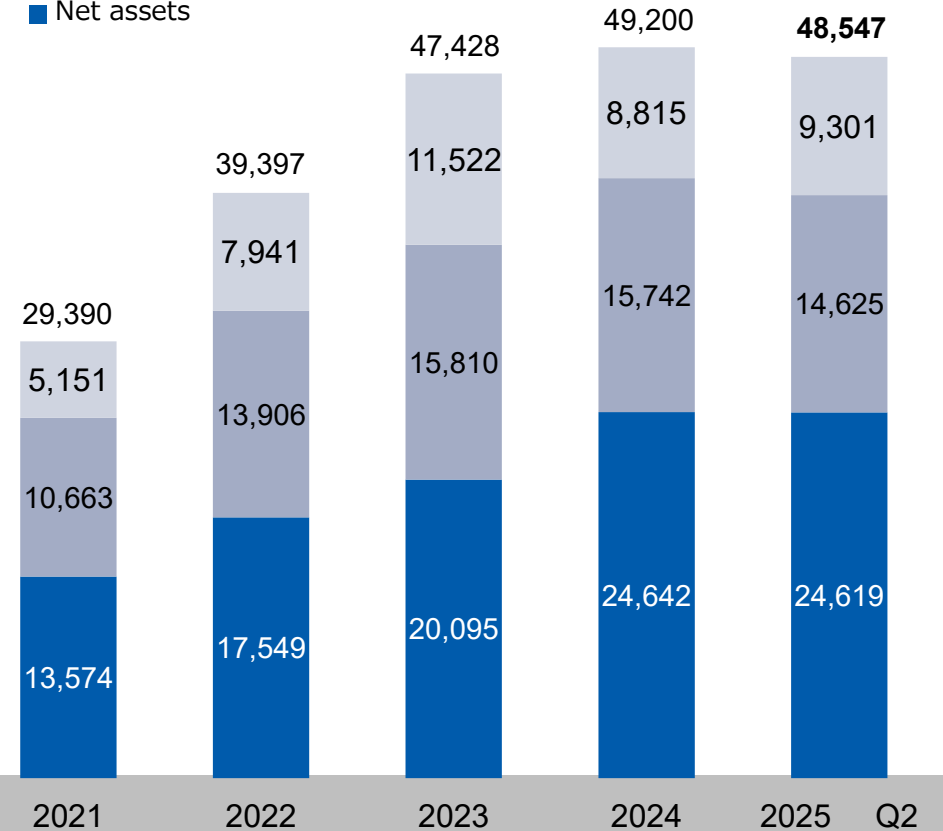
- Cash equivalent
- Trade receivable
- Investors
- Other current assets
- Noncurrent assets



## Liabilities/Equity

(Millions of yen)

- Interest-bearing debt
- Other liabilities
- Net assets





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# Q2 FY2025 Segment Information

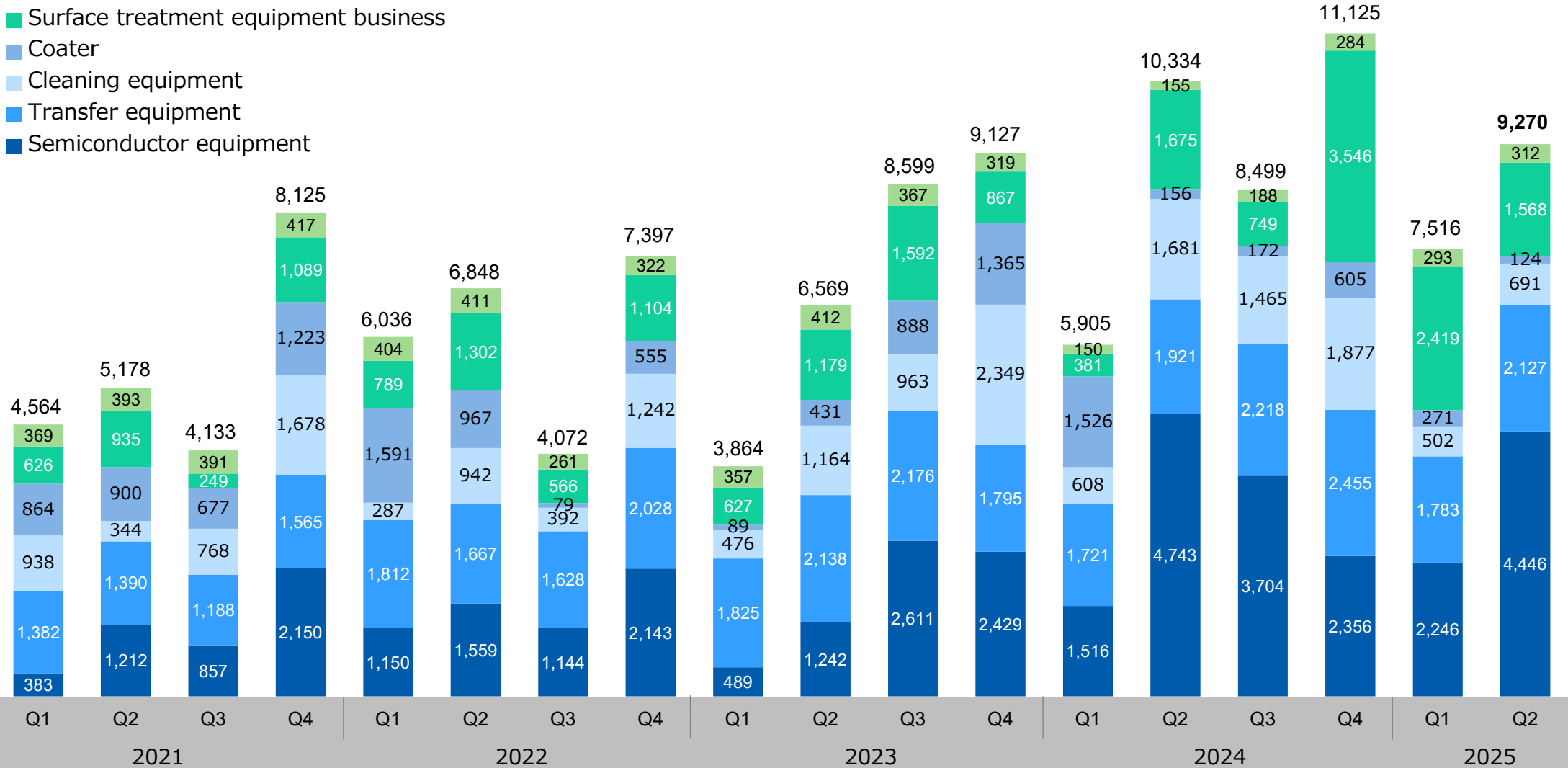
# Net Sales and Operating Profit by Segment

(Millions of yen)		Q2 FY2024	Q2 FY2025	Y o Y	FY2025	vs. Initial H1	FY2025	vs. Full Year
		Actual	Actual	Change(%)	Initial H1 Estimate	Estimate (%)	Full Year Estimate	Estimate (%)
<b>Process equipment business</b>	Net sales	13,877	12,193	△12.1	13,900	87.7	33,000	36.9
	Operating income	2,745	1,920	△30.0	1,550	123.9	4,500	42.7
■ Semiconductor equipment	Net sales	6,260	6,692	6.9	—	—	18,200	36.8
■ Transfer equipment	Net sales	3,643	3,911	7.3	—	—	9,300	42.1
■ Cleaning equipment	Net sales	2,290	1,194	△47.9	—	—	3,700	32.3
■ Coater	Net sales	1,683	396	△76.5	—	—	1,800	22.0
<b>Precision molding dies and plastic moldings business</b>	Net sales	306	606	98.2	540	112.2	1,100	55.1
	Operating income	△101	56	—	20	280.0	50	112.0
<b>Surface treatment equipment business</b>	Net sales	2,056	3,987	93.9	4,200	94.9	6,900	57.8
	Operating income	177	517	191.0	360	143.6	450	114.9
Elimination of inter-segment transactions	Operating income	15	△191	—	—	—	—	—
<b>Total</b>	Net sales	16,239	16,787	3.4	18,640	90.1	41,000	40.9
	Operating income	2,836	2,517	△11.2	1,930	130.4	5,000	50.3

# Trend in Net sales by Segment (Quarterly)

- Precision molding dies and plastic moldings business
- Surface treatment equipment business
- Coater
- Cleaning equipment
- Transfer equipment
- Semiconductor equipment

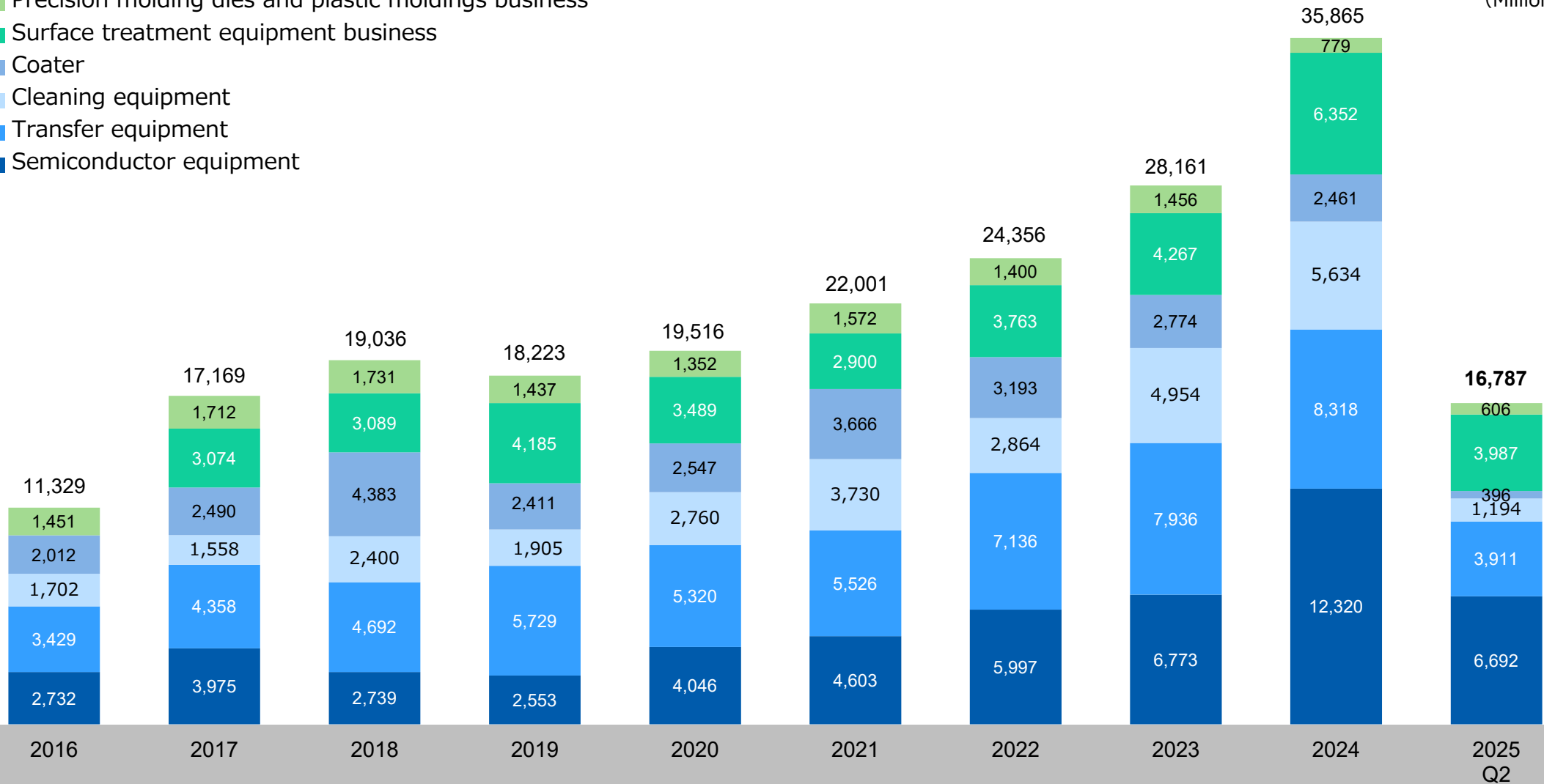
(Millions of yen)



# Trend in Net sales by Segment (Full year)

- Precision molding dies and plastic moldings business
- Surface treatment equipment business
- Coater
- Cleaning equipment
- Transfer equipment
- Semiconductor equipment

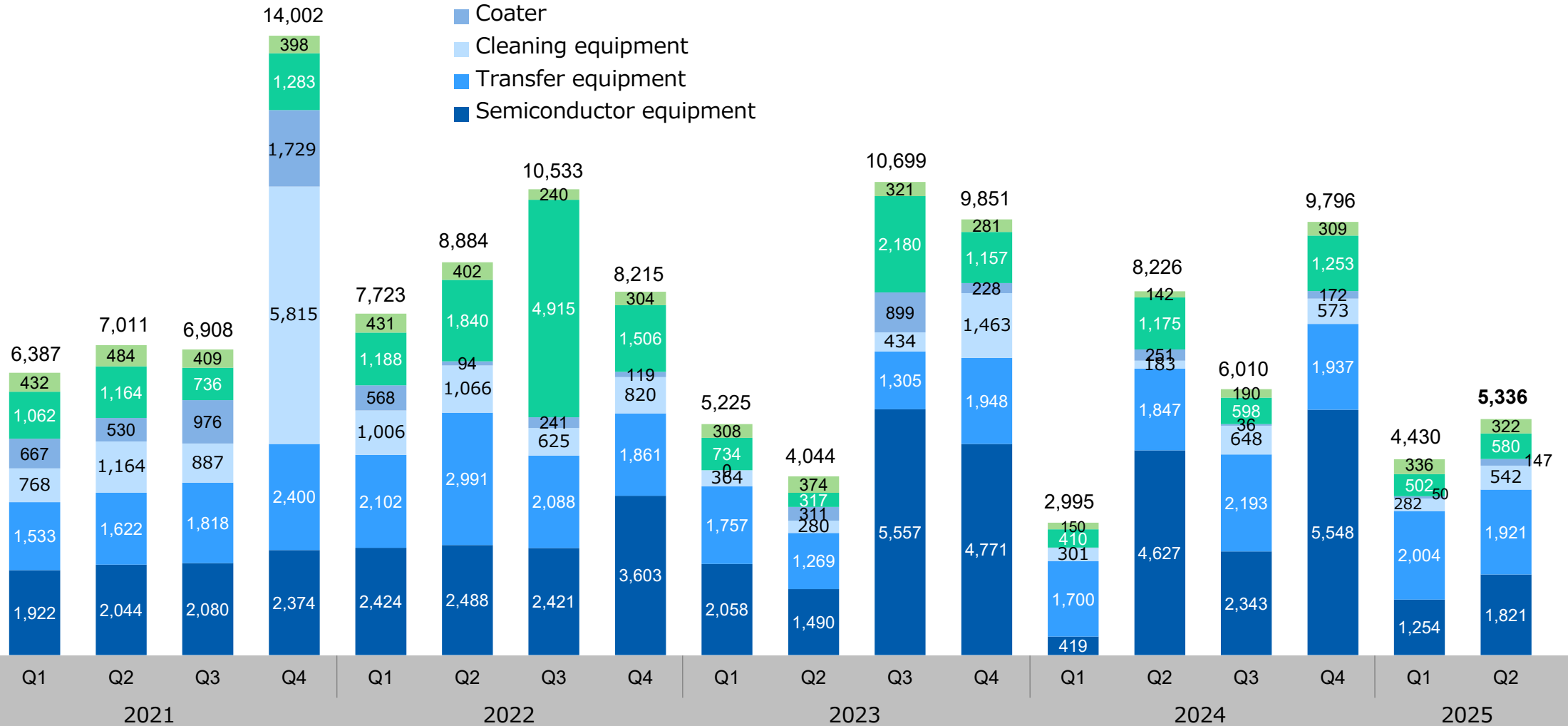
(Millions of yen)



# Trend in Sales Orders by Segment (Quarterly)

(Millions of yen)

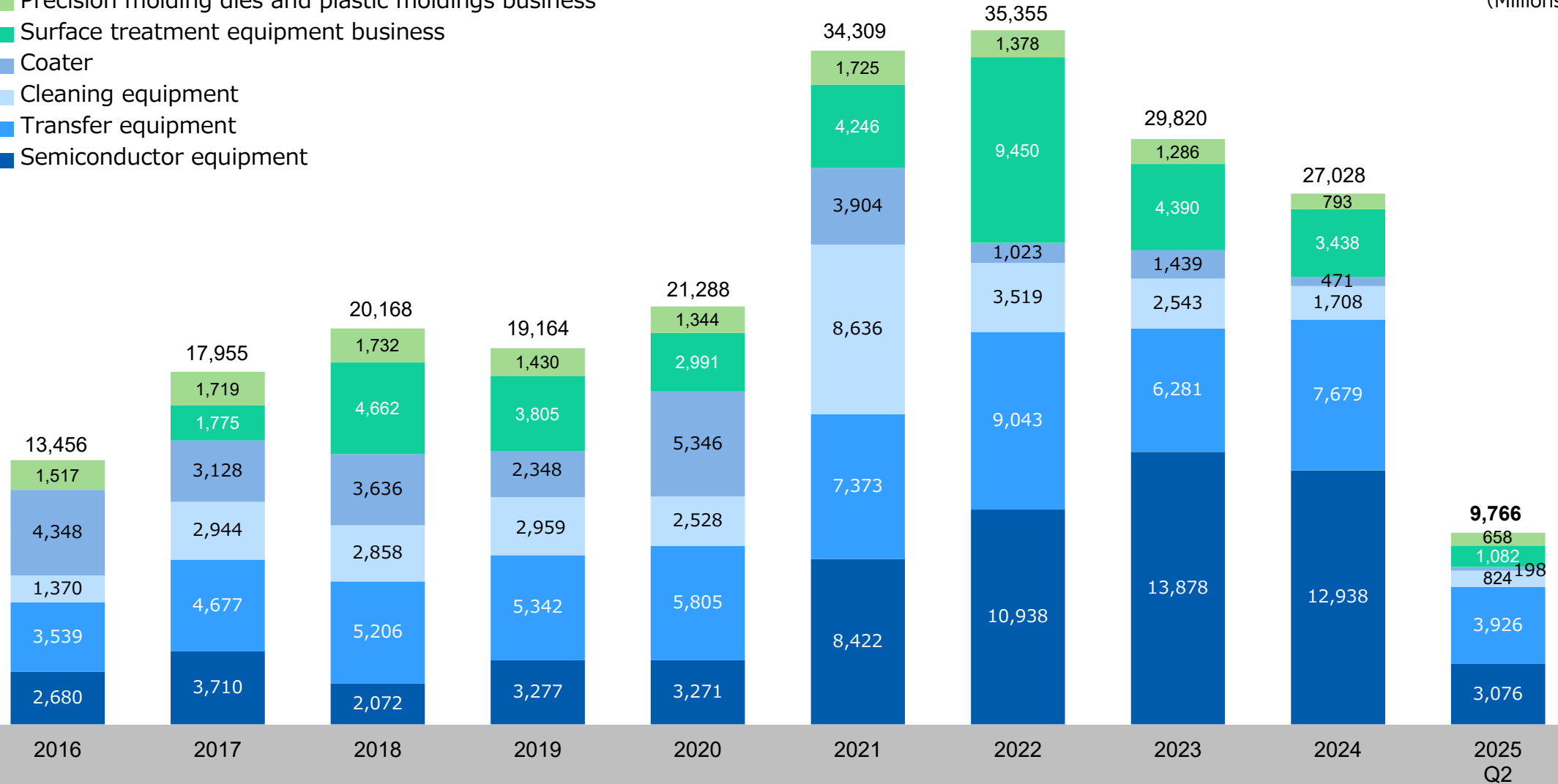
- Precision molding dies and plastic moldings business
- Surface treatment equipment business
- Coater
- Cleaning equipment
- Transfer equipment
- Semiconductor equipment



# Trend in Sales Orders by Segment (Full year)

(Millions of yen)

- Precision molding dies and plastic moldings business
- Surface treatment equipment business
- Coater
- Cleaning equipment
- Transfer equipment
- Semiconductor equipment

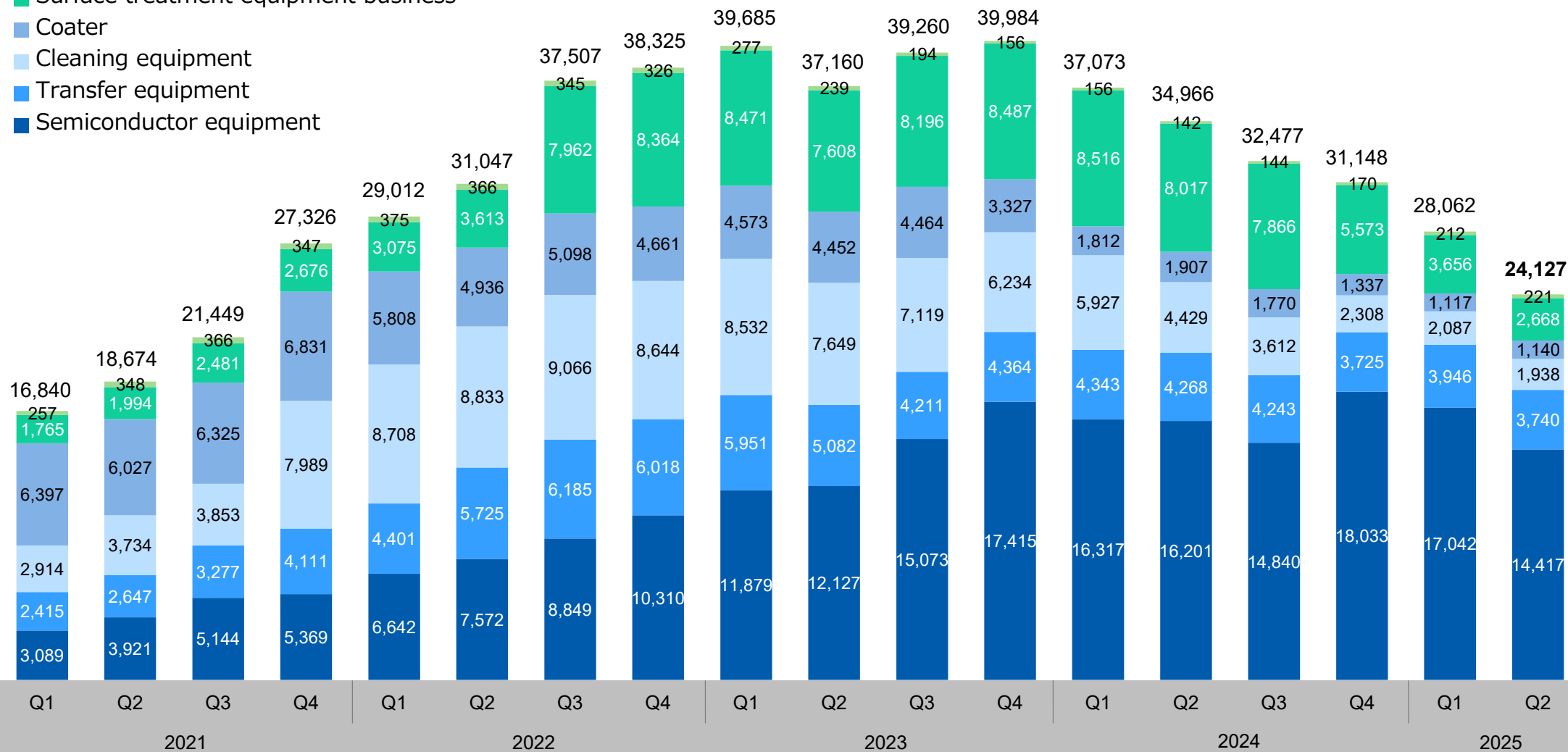




# Trend in Order Backlog by Segment (Quarterly)

(Millions of yen)

- Precision molding dies and plastic moldings business
- Surface treatment equipment business
- Coater
- Cleaning equipment
- Transfer equipment
- Semiconductor equipment





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# Business Environment

- In semiconductor equipment, while there are inquiries for equipment for advanced packaging, order placements have been delayed. For equipment for power semiconductors, inquiries have gradually emerged, mainly in certain regions, and we are closely monitoring future market trends.
- In transfer equipment, the market stagnation and shorter delivery lead times have made order acquisition challenging. In the domestic market, however, orders for high value-added projects such as EFEM are gradually expanding.
- With increasing inquiries for PLP-compatible equipment, we are taking measures to ensure firm order acquisition and expect market expansion going forward. Inquiries for PLP-use robots are also on the rise.
- We are receiving inquiries for phosphoric acid reclamation process equipment and slurry supply equipment. In cleaning equipment, we are actively working to secure orders for new projects.
- In surface treatment equipment, order intake has settled down somewhat due to factors such as the postponement of investment plans for plating processing equipment. We are focusing on new development projects while working to expand orders. In substrate-related transfer equipment, inquiries are increasing as automation advances.

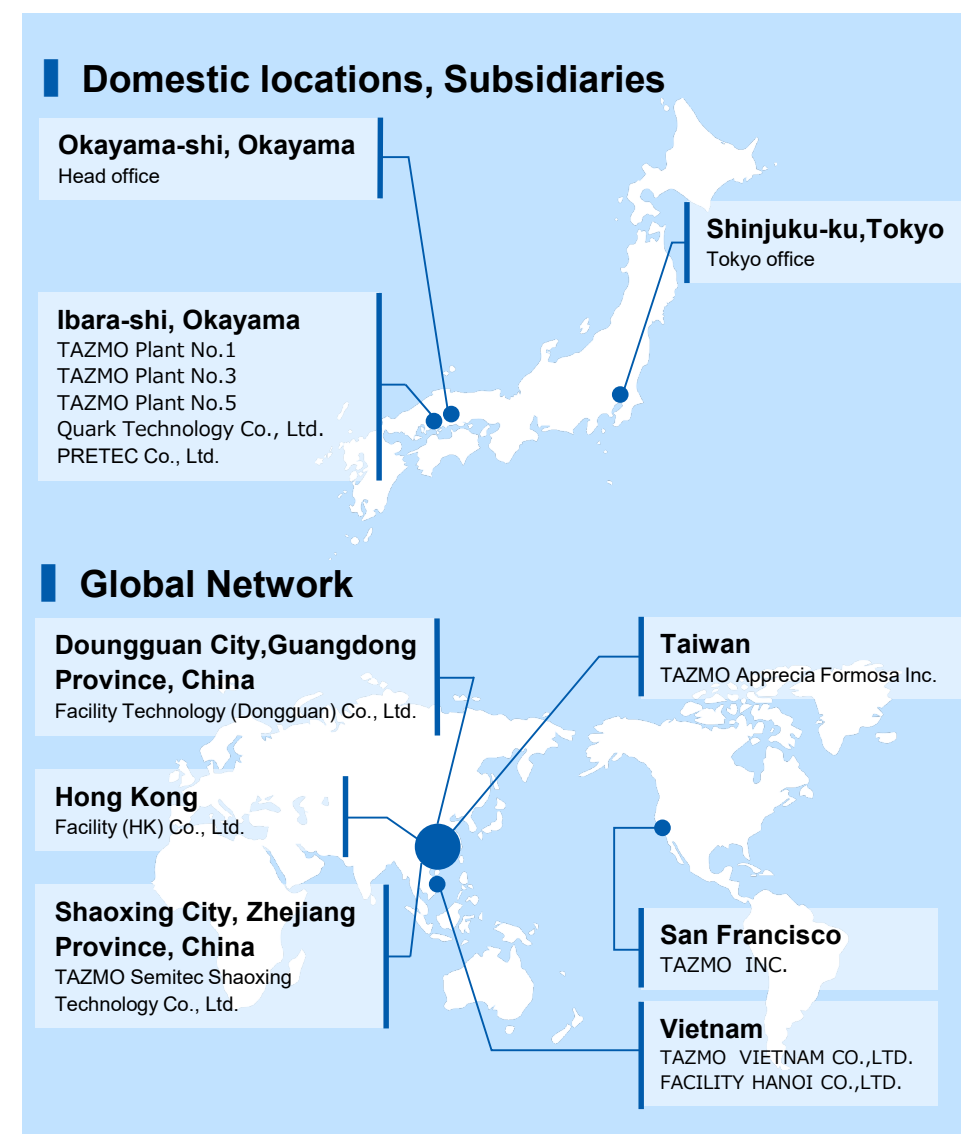


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# Appendix

(as of June 30, 2025)

<b>Company name</b>	TAZMO Co., Ltd.
<b>Established</b>	February 26, 1972
<b>Head office</b>	5311, Haga, Kita-ku, Okayama-shi, Okayama 701-1221, Japan
<b>Capital</b>	356,859,682 yen
<b>Total number of issued shares</b>	14,842,354
<b>Number of shareholders</b>	9,701
<b>Number of employees</b>	Non-consolidated 436 Consolidated 1,180
<b>Business content</b>	Development, Manufacturing and Sales of Semiconductor Manufacturing Equipment, Clean Transfer System, UV Laser Equipment, Plating Equipment, Mold・Resin Molding, Plating/Circuit formation Equipment for PCB



- 1972** ● - TAZMO Co., Ltd. is incorporated to manufacture and produce electronic components and repair industrial equipment.
- 1980** ● - Began production of molding dies, including injection molding dies.
  - Completed development of Fully-automated Photo Resist Coater; production and sales started.
- 1989** ● - Developed TFT Full-color filter manufacturing system; production and sales started.
- 1990** ● - Constructed new head office/plant at 6186 Kinoko-Cho, Ibara, Okayama
  - Developed and produced Ultra Compact Transfer System for Super Clean Room.
- 1994** ● - Began production and sales of Emboss Carrier Tape.
- 1995** ● - Began production of injection Molding Products.
- 2001** ● - Developed "CS13" series Photo Resist Coater specialized for a thicker film application; production and sales started.
- 2004** ● - Listed on the JASDAQ market.
- 2008** ● - Established TAZMO VIETNAM CO., LTD. a consolidated subsidiary, in Ho Chi Minh City, Vietnam.
- 2009** ● - Developed 10th generation compatible full-color filter manufacturing system; production and sales started.
  - Concluded a license agreement with 3M(USA) for semiconductor manufacturing equipment.
- 2013** ● - Apprecia Technology Inc. became our wholly owned subsidiary company.
  - VIETNAM CO., LTD. Constructed new factory at Long Hau Industrial Park in Long An Province, Vietnam.
- 2017** ● - Facility Co., Ltd. and Quark Technology Co., Ltd. became our wholly owned subsidiary company.
- 2018** ● - Listed on the First Section of the Tokyo Stock Exchange
- 2019** ● - Constructed a new head office at 5311 Haga Kita-ku, Okayama-shi, Okayama
- 2020** ● - Merged with Apprecia Technology Inc.
- 2022** ● - TAZMO's listing transferred to Prime Market in Tokyo Stock Exchange.
  - Increased capital to 3,495,400,000 yen through public offering.
  - Established TAZMO SEMITEC SHAOXING TECHNOLOGY Co., Ltd. a consolidated subsidiary, in Zhejiang Shaoxing, China.

We develop, manufacture, and sell equipment for manufacturing cutting-edge semiconductors and packages, as well as clean transfer robots.

## Semiconductor Manufacturing Equipment Business Unit

Using the know-how and technology cultivated over 40 years, we provide equipment for various processes such as coating, developing, laminating, and peeling in semiconductor manufacturing worldwide.



## Transfer Business Unit

Providing various transport systems that are accurate, speedy, and space-saving, including transport robots for silicon wafers, etc., which are essential for semiconductor manufacturing.



## Cleaner Business Unit

Providing silicon wafer cleaning and slurry supply equipment, which is an important process in semiconductor manufacturing, as well as equipment that regenerates and reuses phosphoric acid from waste liquid.



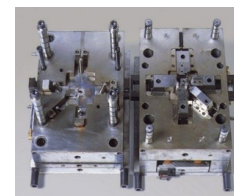
## Coater Business Unit

Leveraging our expertise in supplying various flat panel display manufacturing equipment, we provide PLP and nanoimprint equipment.



## Molding Business

Mold technology, which is essential for parts manufacturing, has been a core technology since our founding, and we provide a variety of products to meet the various needs of user companies.



## Surface Treatment Business

Providing plating processing equipment for printed circuit boards incorporated in semiconductor packages and electronic control systems for automobiles, etc.



## Attention

Forward-looking statements with respect to TAZMO's business plan, prospects and other such information are based on information available at the time of publication. Actual performance and results may differ significantly from the business plan described here due to changes in various external and internal factors.

This material takes as its objective the provision of information regarding the management policy, plans, and financial situation of KDDI to shareholders, investors and other visitors. It constitutes neither an offer nor a solicitation to purchase or sell TAZMO stock.

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